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FORM PTO-1595

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U.S. Department of Commerce

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OMB No. 0651-011 (exp. 4/94)

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Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Robert Weixiu Du  
Chinping Q. Yang

05/30/01

Additional name(s) of conveying party(ies)

attached? \_\_\_ Yes X No

2. Name and address of receiving party(ies):

Name: Sony Corporation and Sony Electronics Inc., jointly.

As to Sony Corporation:

Street Address: 6-7-35 Katashinagawa, Shinagawa-Ku

City: Tokyo Country: JAPAN

As to Sony Electronics Inc.:

Street Address: 1 Sony Drive

City: Park Ridge State: NJ ZIP 07656-8003

Additional name(s) & address(es) attached? \_\_\_ Yes X No

3. Nature of conveyance:

X Assignment \_\_\_ Merger

\_\_\_ Security Agreement \_\_\_ Change of Name

\_\_\_ Other \_\_\_\_\_

Execution Date: May 24, 2001

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is May 24, 2001

A. Patent Application No.(s)

B. Patent No.(s)

09/867735

Additional numbers attached? \_\_\_ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:

Thomas W. Humphrey  
Wood, Herron & Evans, L.L.P.  
2700 Carew Tower  
Cincinnati, Ohio 45202

6. Total number of applications and patents involved: 1

7. Total Fee (37 CFR 3.41)-----\$ 40.00

X Enclosed

\_\_\_ Authorized to be charged to deposit account

8. Deposit Account Number: 23-3000

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Thomas W. Humphrey

*Thomas W. Humphrey*

358 May 30, 2001

Name of Person Signing

Signature & Reg. No.

Date

Total number of pages comprising cover sheet, attachments, and document: 5

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks, Box Assignments, Washington, D.C. 20231

*Wey...*

PATENT

REEL: 011863 FRAME: 0571

Vertical stamp: JC929 U.S. PTO 09/867735 05/30/01

## ASSIGNMENT

**WHEREAS, I**, as a below named inventor, residing at the address stated below my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in **MEMORY SHARING SCHEME IN AUDIO POST-PROCESSING** for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

**AND WHEREAS, SONY CORPORATION**, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan, and **SONY ELECTRONICS INC.**, a corporation organized under the laws of the state of Delaware, and having its principal place of business at 1 Sony Drive, Park Ridge, New Jersey 07656 (hereinafter "**ASSIGNEES**"), desire to acquire all interest in, to and under said invention, said application disclosing the invention, and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

**NOW, THEREFORE**, in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said **ASSIGNEES**, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said **ASSIGNEES**, as the assignees of the whole right, title and interest thereto.

And I further agree to execute all necessary or desirable and lawful future documents, including assignments, in favor of **ASSIGNEES** or its designee, as **ASSIGNEES** or its successors, assigns and legal representatives may from time to time present to me, without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto.



